

GRAPHICS MEMORY PART-NUMBER DECODER

H 5 X X XX X X X X - XX X
 1 2 3 4 5 6 7 8 9 10 11 12 13 14

SK HYNIX MEMORY

PRODUCT FAMILY

5 : DRAM

PRODUCT MODE

T : DDR3 G : GDDR5

: GDDR5 SDRAM

POWER SUPPLY

C : VDD=1.35V & VDDQ=1.35V
 Q : VDD=1.5V & VDDQ=1.5V

DENSITY & REFRESH

2G : 2Gb, 8K/64ms Refresh	1H : 1Gb, 8K/32ms Refresh
4G : 4Gb, 8K/64ms Refresh	2H : 2Gb, 16K/32ms Refresh
8G : 8Gb, 8K/64ms Refresh	4H : 4Gb, 16K/32ms Refresh
16 : 16Gb	8H : 8Gb, 16K/32ms Refresh
32 : 32Gb	
64 : 64Gb	

ORGANIZATION

6 : x16
 2 : x32

NUMBER OF BANKS

3 : 8 Banks
 4 : 16 Banks

DIE GENERATION

M : 1st	D : 5th
A : 2nd	E : 6th
B : 3rd	F : 7th
C : 4th	G : 8th

OPERATING TEMPERATURE & POWER CONSUMPTION

C : Commercial Temp¹⁾ & Normal Power

SPEED

11 : 900MHz	T0 : 2.0GHz
N0 : 1.0GHz	T2 : 2.5GHz
N1 : 1.1GHz	R0 : 3.0GHz
N2 : 1.2GHz	R2 : 3.5GHz
N3 : 1.3GHz	R4 : 4.0GHz
N4 : 1.4GHz	
N5 : 1.5GHz	
N6 : 1.6GHz	

PACKAGE MATERIAL

R : Lead Free & Halogen Free
 (ROHS²⁾ compliant)

PACKAGE TYPE

F : FBGA SDP
 (Single Die Package)
 M : FBGA DDP
 (Double Die Package)
 J : FCBGA
 (Flipchip)

Note:
 1) Commercial Temperature: 0°C ~ 85°C
 2) ROHS : Restriction Of Hazardous Substances